20. The electrical apparatus of Claim 8, wherein said electrically insulating component is a package body that contains said electrical device.

21. The electrical apparatus of Claim 8, wherein said electrically insulating component is a substrate upon which said electrical device is supported.

## REMARKS

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-17 were pending in this application. Non-elected Claims 13-17 have been cancelled without prejudice. New Claims 18-21 have been added. Claims 1 and 8 have been amended to better define the scope of the claimed invention.

Applicant hereby affirms the election of Claims 1-12 and withdrawal from consideration of Claims 13-17. Claims 13-17 have been cancelled.

The drawings were objected to. Drawing corrections are attached to this response in red ink. Applicant requests consideration and entry of the drawing amendments.

Claims 2-6 and 9-12 stand rejected under 35 U.S.C. 112, second paragraph. Applicant respectfully traverses the rejection. The Examiner asserted that in the phrase "substrate included in an electrical product", it is not clear whether the substrate itself is an electrical product or whether the substrate and the electrical product are different elements. Applicant submits that it is clear that the substrate and the electrical product are different elements. The substrate is a part of the electrical product having the function of affixing the

electrical apparatus. The Examiner also asserted that in the phrase "substrate is embodied in a chemical compound material", it is not clear whether the chemical compound is used as an element in the substrate or whether the substrate is coated by a chemical compound. Applicant submits that for the substrate to be "embodied in a chemical compound", the substrate is formed with the chemical compound. Thus, if the substrate comprises multiple layers, for example, the phrase could describe a structure in which one of the layers of the substrate comprises the chemical compound. On the other hand, if the substrate is uniform throughout, the phrase could describe the chemical compound of which the substrate is formed. Regardless of the interpretation, Applicant respectfully submits that the phrase is clear in describing a substrate formed with the chemical compound. The same reasoning applies to the phrase "substrate embodied in a chemical mixture material." Therefore, Applicant respectfully requests that the rejection of Claims 2, 3, 9, and 10 be withdrawn.

Claims 1-12 stand rejected under 35 U.S.C. 103(a) as being unpatentable over what the Examiner refers to as "the prior art figure 1-4 disclosed by applicant" in view of Cheng, et al. (U.S. Patent No. 6,344,157) and Kobayashi, et al. (U.S. Patent No. 4,821,148). Applicant respectfully traverses the rejection. Figures 1-4 of the instant application are not labeled prior art, and have not been acknowledged to be prior art by Applicant. Therefore, Applicant respectfully requests that the Examiner set forth the basis upon which the Examiner has determined those Figures to be prior art. Claim 1, as amended, includes the feature of "a package structure comprising an electrically insulating component, said package structure substantially enclosing said at least one electrical device; the improvement comprising: involving a corrosion-resisting agent with said electrically insulating component of said package structure." Claim 8 includes the feature of "a packaging structure comprising an electrically insulating component; said packaging structure substantially enclosing said at least one electrical device; said electrically insulating component of said packaging structure including a corrosion-resisting agent." Cheng does not teach or

suggest such features. Cheng is concerned with preventing an increase in the resistance of conductors and resistors. In contrast, in claims 1 and 8 a corrosion-resisting agent is involved in an *insulating* component rather than in a conductor or resistor. Cheng's teachings of techniques of avoiding an increase in resistivity does not apply to insulators, where an increase in resistivity would be of no consequence, so Applicant submits that one skilled in the art would receive no motivation to apply Cheng's teachings to Applicant's Figures 1-4 (assuming only for the sake of argument that Figures 1-4 are in the prior art). Kobayashi teaches applying films of benzotriazole to electrodes and wires, and thus is unrelated to involving a corrosion-resisting agent in an insulating component. Thus, one skilled in the art would receive no motivation to apply Kobayashi's teachings to Applicant's Figures 1-4 or to Cheng's similar teachings. For at least these reasons, Applicant respectfully submits that Claims 1 and 8 are patentable over the cited combination of references. Support for the amendments to Claims 1 and 8 may be found on page 4 of the specification at lines 1-4, where it is stated that contact structures 54 are electrically discrete within body 52. Similarly, it is clear from Figure 4 that substrate 114 is electrically insulating; otherwise, contact structures 49 would be electrically connected (i.e. short circuited) by the substrate.

Claims 2-7, 9-12, and 18-21 depend from Claims 1 and 8 and are therefore patentable over the cited combination for at least the reasons presented above. New Claims 18-21 find support on page 7 of the specification from lines 5 to 15.

Applicant respectfully requests reconsideration and withdrawal of the rejections and allowance of Claims 1-12 and 18-21. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,

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## VERSION WITH MARKINGS TO SHOW CHANGES MADE

**In the Claims:**

1. (amended) An improved electrical apparatus configured for resistance to atmospheric effects; the apparatus including at least one electrical device and a package structure comprising an electrically insulating component, said package structure substantially enclosing said at least one electrical device; the improvement comprising: involving a corrosion-resisting agent with said electrically insulating component of said package structure.

8. (amended) An electrical apparatus having resistance to atmospheric effects; the apparatus comprising at least one electrical device and a packaging structure comprising an electrically insulating component; said packaging structure substantially enclosing said at least one electrical device; said electrically insulating component of said packaging structure including a corrosion-resisting agent.

Please add the following new claims:

18. The electrical apparatus of Claim 1, wherein said electrically insulating component is a package body that contains said electrical device.

19. The electrical apparatus of Claim 1, wherein said electrically insulating component is a substrate upon which said electrical device is supported.

20. The electrical apparatus of Claim 8, wherein said electrically insulating component is a package body that contains said electrical device.

21. The electrical apparatus of Claim 8, wherein said electrically insulating component is a substrate upon which said electrical device is supported.